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600584



99



200

39

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[www.sse.com.cn](http://www.sse.com.cn)

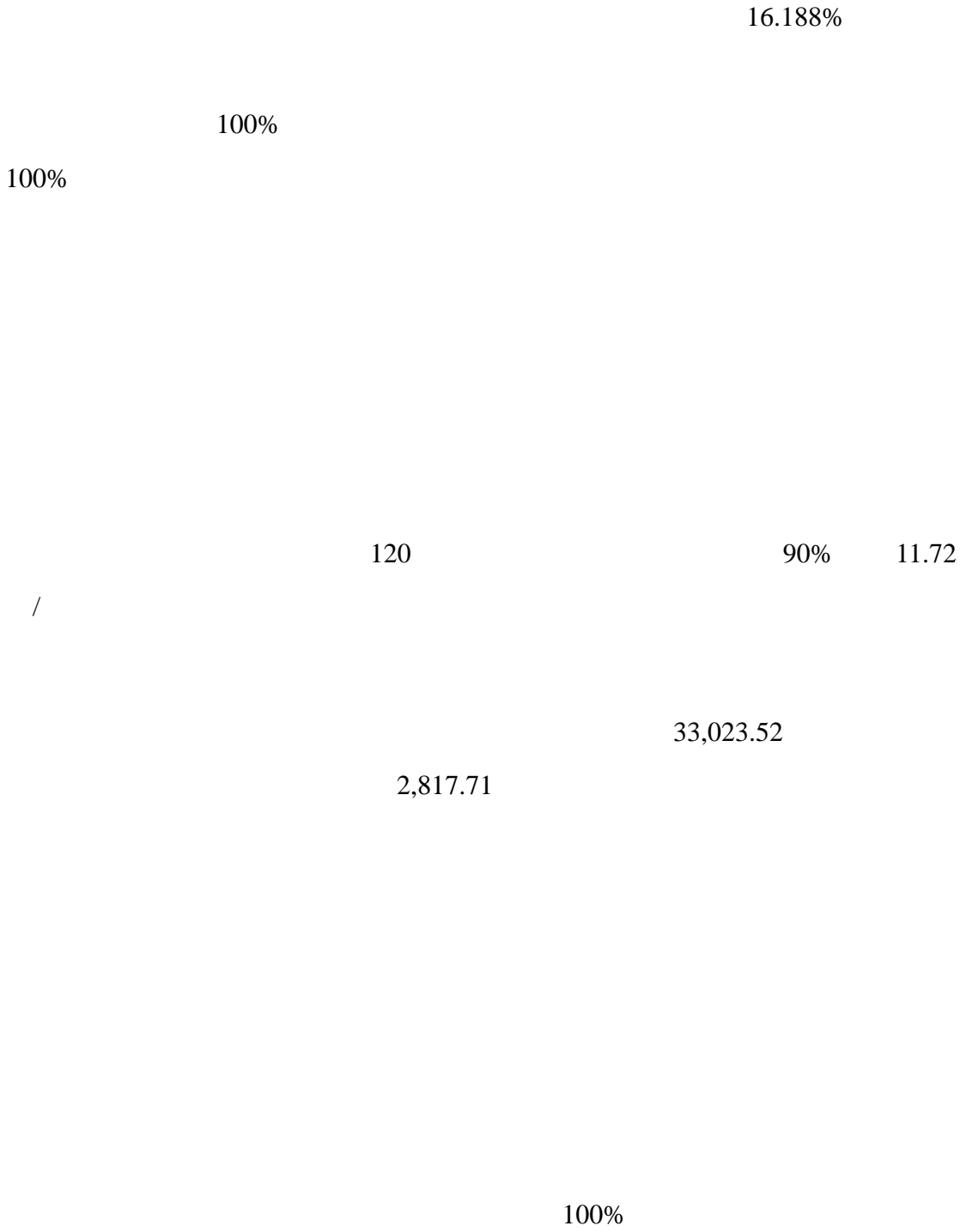
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.....	<b>1</b>
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.....	<b>3</b>
.....	<b>6</b>
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.....	14
.....	16



		2014
		STATS ChipPAC Ltd.
APS		ADVANPACK SOLUTIONS PTE LTD.
		2012    2013    2014    2015    1-4
		2013    2014    2015    1-4
		4    5    6 8    12
IDM		
FC		Flip-Chip
BUMPING		
WLCSP		Wafer level Chip size package

TSV		Through Silicon Via
SIP		Single In-line Package
SiP		System in a Package
DIP		Dual in-line Package
TO		Transistor out-line
SOP		Small Out-Line Package
SSOP		
PLCC		plastic leaded chip carrier
QFN		Quad Flat Non-leaded package
QFP		Quad Flat Package
BGA		ball grid array
WLP		Wafer Level Package
CSP		Chip Scale Package
MCM		Multi-Chip Module
LED		



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20

90%

14.14 /

33,023.52

33,023.52

2,335.47

48

50%

16.188%

2015 4

1.92%

APS

3.812%

2014

	16.188%	1.92%	3.812%			
	33,023.52	3,838.50	7,608.83	44,470.85	1,090,230.47	4.08%
	33,023.52	3,838.50	7,608.83	44,470.85	376,385.09	11.82%
	23,254.92	2,758.18	5,476.14	31,489.24	642,827.33	4.90%

2015 4 30

33,023.52

36

6

20

6

6

36

/

2014

143,655.27

22.35% 2014 17,229.40

82.53%

76.92% 6.892%

100%

98,457.00

2,817.71 11.72 /

2,335.47 14.14 /

	13,892.74	14.11%	19,045.92	18.38%
	84,564.26	85.89%	84,564.26	81.62%
	<b>98,457.00</b>	<b>100%</b>	<b>103,610.17</b>	<b>100%</b>

14.11%

18.38%

1

2

3

4

		1		420.888
		2	16.188%	
		3		
		4		
		1	36	6 20
				6 6
		2		36
				2015 2016
			2017	
			16.188%	
		1	/	

		2 /	/
		1 / /	
		2 / / /	
		3 /	
		4 /	/
		/ /	
		/ /	
		/ /	
			/

1

2



4

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2015 4 7

2015 5 21

2015 5 19



1

2

6

3

	2015	4	30	11,646.99
33,023.52			21,376.53	183.54%



2008

20

-0.4% 2009

2010

18-24



FC			QFN		FCOL		FCOS		WL-CSP	
					APS					20
2003	8	7	2023	8	7					

8

APS

90%



